



To submit a nomination for the EDI CON Product Innovation Awards, fill out the information below and email it and a product photo to Sonia Thai:

sthai@mwjournal.com

Subject Line: EDI CON China Awards Nomination

Deadline: Friday, February 28, 2020

Note: Your company must be exhibiting at EDI CON CHINA 2020 to participate.

Company Name:

Company Mailing Address:

Product Name:

Product URL:

Product Release Date (must be during 2018):

Press Release URL:

Product Award Category:

- Test & Measurement
- Software/EDA
- Semiconductors
- Components, Cables, & Connectors
- Materials, PCBs and Packaging

Contact Name:

Contact Email:

Contact Phone:

What is the Product's function?

What are its competitive advantages and why should it be nominated and recognized?

Select One:

- New Product
- New Generation of existing Product

Attach a JPG of the Product: